ABSTRACT

The present disclosure relates to the technical field of semiconductors, and provides a package substrate and a semiconductor structure with the package substrate. The package substrate includes a body (10) and a conductive layer (20). The body (10) includes an opening region (11). The conductive layer (20) is disposed at the opening region (11). The conductive layer (20) includes a first conductive bridge (21) and a second conductive bridge (22). The first conductive bridge (21) and the second conductive bridge (22) are disposed at intervals. The first conductive bridge (21) is provided with at least one first via (211). The first conductive bridge (21) and the second conductive bridge (22) are disposed at intervals in the opening region (11).

Fig. 1